

# Tervetuloa O-johtavaan

O-Leading pyrkii olemaan yhden luokun ratkaisukumppani EMS-toimitusketjussa, mukaan lukien piirilevyjen suunnittelu, piirilevyjen valmistus ja piirilevyjen kokoaminen (PCBA). Tarjoamme joitain edistyneimmistä piirilevyteknikoista, mukaan lukien HDI-piirilevyt, monikerroksiset piirilevyt, jäykät ja joustavat piirilevyt. Voimme tukea prototyypin nopeasta kääntämisestä keskisuurten ja massatuotantoon.

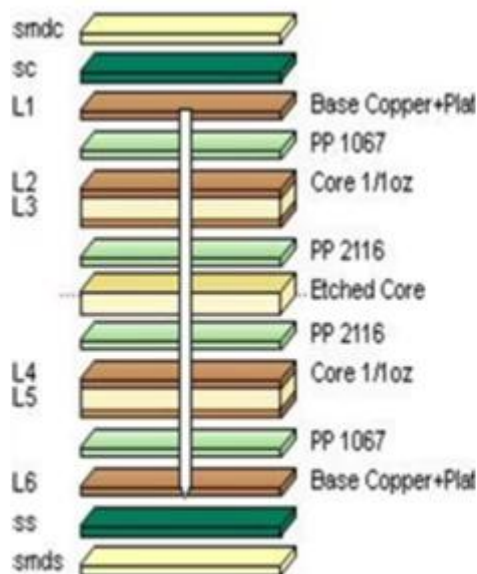
Yleisesti ottaen globaalit asiakkaamme ovat erittäin vaikuttuneita palveluistamme: nopea reagointi, kilpailukykyinen hinta ja sitoutuminen laatuun. Arvokkaamman teknisen palvelun ja kokonaisratkaisun tarjoaminen on O-tapa edetä.

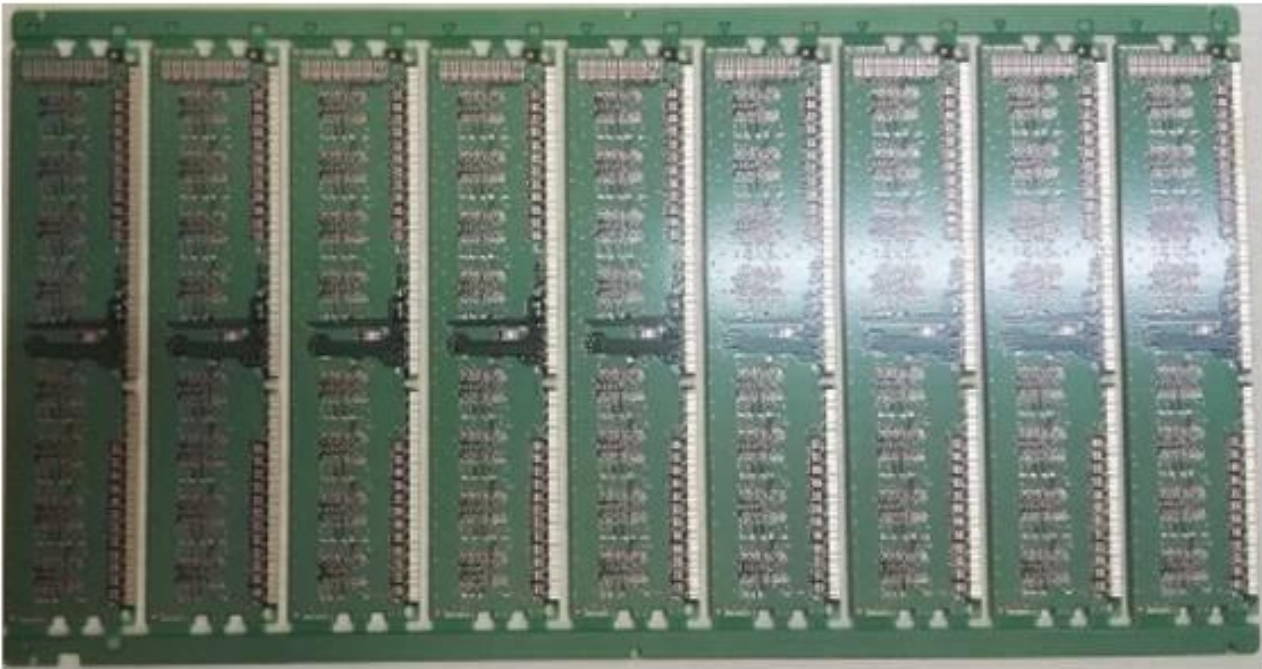
Tulevaisuuden näkökulmasta O-johtava keskittyy aina elektroniikan valmistustekniikan innovaatioihin ja kehitykseen ja pyrkii jatkuvasti PCB:n ja PCBA:n keskitettyyn palveluun tarjoamaan ensiluokkaisia palveluita ja luomaan enemmän arvoa asiakkaillemme.

KUPARIYTYSEN REIKAT MINIMAALISET .025 AVG, .020 MIN .. reikiä EI SAA kytkeä

Pakkaus värittömällä läpinäkyvällä kuplakalvolla, 25 kpl / pussi, laita kuivausaine kylkeen, laita kosteuden ilmaisinkortti yläpuolelle

Kerroksen rakenne





[www.o-leading.com](http://www.o-leading.com)

[pcb-valmistaja Kiinassa](#)

Tiimimme



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Factory PCB

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Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

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Factory SMT

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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



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Test Report

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Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium, Lead, Mercury, Hexavalent Chromium, Sum of PBBs, etc. with their respective limits and detection results.



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## ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

## Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**O-LEADING SUPPLY CHAIN (HK) CO LTD**

E490354

ROOM 1205, 12/F  
TAI SANG BANK BLDG  
130-132 DES VOEUS ROAD  
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max		Meets	C	I	
	Min	Edge			Area	Solder	Oper				Flame
	mm(in)	mm(in)			Diam mm(in)	Limits C	Temp sec	Class C	UL796 DSR	T	
<b>Multilayer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
<b>Multilayer printed wiring boards.</b>											
<b>O-LEADING-408</b>	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
<b>O-LEADING-003</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
<b>O-LEADING-205</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-206</b>	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-D01</b>	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
<b>O-LEADING-S01</b>	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

## WIRING, PRINTED - COMPONENT | UL Product iQ

<b>O-LEADING-S02</b>	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
<b>O-LEADING-S03</b>	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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## Shipping service





Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

## Prosessin kyky

### Piirilevyjen tuotantokapasiteetit

Kerrosäärä: 1-kerros-32-kerros

Valmiiden kuparien paksuus □ 1 / 3oz-12oz

Min Rivin leveys / etäisyys sisäinen □ 3,0mil / 3,0mil

Min Rivin leveys / välinen etäisyys: 4,0mil / 4,0mil

Suurin kuvasuhde: 10: 1

Levyn paksuus □ 0,2-5,0 mm

Paneelin enimmäiskoko (tuumaa): 635 \* 1500 mm

Poratun reiän vähimmäiskoko: 4mil

PI-reikätoleranssi: +/- 3mil

Blind / Buried Vias (All-tyypit): YES

Täyttämällä (johtava, johtamaton): KYLLÄ

Pohjamateriaali: FR-4, FR-4korkean painon halogeeniton materiaali, Rogers, alumiininen pohja,polyimidi,  
Raskas kupari

Pintakäsittelyt: HASL, OSP, ENIG, HAL-LF, hopea,Lummersion Tina, kultaiset sormet, hiilimuste

### SMT-tuotantokapasiteetit

Piirilevymateriaali: FR-4, CEM-1, CEM-3, alumiinipohjainen levy  
Suurin piirilevyn koko: 510x460 mm  
Minimi piirilevyn koko  $\square$  50x50mm  
Piirilevyn paksuus  $\square$  0,5-4,5 mm  
Levyn paksuus  $\square$  0,5-4mm  
Komponenttien vähimmäiskoko: 0201  
Tavallinen sirukoko-komponentti: 0603 ja suurempi  
Komponentin enimmäiskorkeus  $\square$  15mm  
Pienin lyijyväli: 0,3 mm  
Minimi BGA-palloväli: 0,4 mm  
Sijoituksen tarkkuus: +/- 0,03 mm